

IRG4BC20KD

INSULATED GATE BIPOLAR TRANSISTOR WITH
ULTRAFAST SOFT RECOVERY DIODE

Short Circuit Rated
UltraFast IGBT

Features

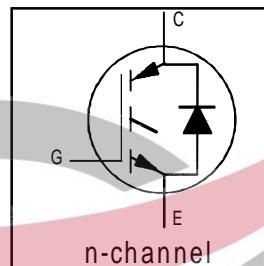
- Short Circuit Rated UltraFast: Optimized for high operating frequencies >5.0 kHz , and Short Circuit Rated to 10 μ s @ 125°C, V_{GE} = 15V
- Generation 4 IGBT design provides tighter parameter distribution and higher efficiency than previous generation
- IGBT co-packaged with HEXFRED™ ultrafast, ultra-soft-recovery anti-parallel diodes for use in bridge configurations
- Industry standard TO-220AB package

Benefits

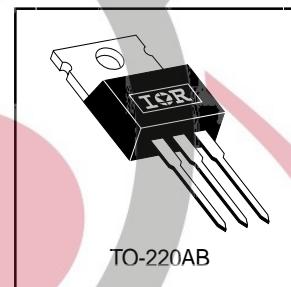
- Latest generation 4 IGBTs offer highest power density motor controls possible
- HEXFRED™ diodes optimized for performance with IGBTs. Minimized recovery characteristics reduce noise, EMI and switching losses
- This part replaces the IRGBC20KD2 and IRGBC20MD2 products
- For hints see design tip 97003

Absolute Maximum Ratings

	Parameter	Max.	Units
V _{CES}	Collector-to-Emitter Voltage	600	V
I _C @ T _C = 25°C	Continuous Collector Current	16	A
I _C @ T _C = 100°C	Continuous Collector Current	9.0	
I _{CM}	Pulsed Collector Current ①	32	
I _{LM}	Clamped Inductive Load Current ②	32	
I _F @ T _C = 100°C	Diode Continuous Forward Current	7.0	μs
I _{FM}	Diode Maximum Forward Current	32	
t _{sc}	Short Circuit Withstand Time	10	
V _{GE}	Gate-to-Emitter Voltage	± 20	
P _D @ T _C = 25°C	Maximum Power Dissipation	60	W
P _D @ T _C = 100°C	Maximum Power Dissipation	24	
T _J	Operating Junction and	-55 to +150	
T _{STG}	Storage Temperature Range		°C
	Soldering Temperature, for 10 sec.	300 (0.063 in. (1.6mm) from case)	
	Mounting Torque, 6-32 or M3 Screw.	10 lbf·in (1.1 N·m)	



V_{CES} = 600V
V_{CE(on)} typ. = 2.27V
@V_{GE} = 15V, I_C = 9.0A



Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units
R _{θJC}	Junction-to-Case - IGBT	—	—	2.1	°C/W
R _{θJC}	Junction-to-Case - Diode	—	—	3.5	
R _{θCS}	Case-to-Sink, flat, greased surface	—	0.50	—	
R _{θJA}	Junction-to-Ambient, typical socket mount	—	—	80	
Wt	Weight	—	2 (0.07)	—	g (oz)

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Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(\text{BR})\text{CES}}$	Collector-to-Emitter Breakdown Voltage③	600	—	—	V	$V_{\text{GE}} = 0\text{V}$, $I_C = 250\mu\text{A}$
$\Delta V_{(\text{BR})\text{CES}/\Delta T_J}$	Temperature Coeff. of Breakdown Voltage	—	0.49	—	V/ $^\circ\text{C}$	$V_{\text{GE}} = 0\text{V}$, $I_C = 1.0\text{mA}$
$V_{\text{CE}(\text{on})}$	Collector-to-Emitter Saturation Voltage	—	2.27	2.8	V	$I_C = 9.0\text{A}$ $V_{\text{GE}} = 15\text{V}$
		—	3.01	—		$I_C = 16\text{A}$ See Fig. 2, 5
		—	2.43	—		$I_C = 9.0\text{A}$, $T_J = 150^\circ\text{C}$
$V_{\text{GE}(\text{th})}$	Gate Threshold Voltage	3.0	—	6.0		$V_{\text{CE}} = V_{\text{GE}}$, $I_C = 250\mu\text{A}$
$\Delta V_{\text{GE}(\text{th})}/\Delta T_J$	Temperature Coeff. of Threshold Voltage	—	-10	—	mV/ $^\circ\text{C}$	$V_{\text{CE}} = V_{\text{GE}}$, $I_C = 250\mu\text{A}$
g_{fe}	Forward Transconductance ④	2.9	4.3	—	S	$V_{\text{CE}} = 100\text{V}$, $I_C = 9.0\text{A}$
I_{CES}	Zero Gate Voltage Collector Current	—	—	250	μA	$V_{\text{GE}} = 0\text{V}$, $V_{\text{CE}} = 600\text{V}$
		—	—	1000		$V_{\text{GE}} = 0\text{V}$, $V_{\text{CE}} = 600\text{V}$, $T_J = 150^\circ\text{C}$
V_{FM}	Diode Forward Voltage Drop	—	1.4	1.7	V	$I_C = 8.0\text{A}$ See Fig. 13
		—	1.3	1.6		$I_C = 8.0\text{A}$, $T_J = 150^\circ\text{C}$
I_{GES}	Gate-to-Emitter Leakage Current	—	—	± 100	nA	$V_{\text{GE}} = \pm 20\text{V}$

Switching Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
Q_g	Total Gate Charge (turn-on)	—	34	51	nC	$I_C = 9.0\text{A}$
Q_{ge}	Gate - Emitter Charge (turn-on)	—	4.9	7.4		$V_{\text{CC}} = 400\text{V}$ See Fig.8
Q_{gc}	Gate - Collector Charge (turn-on)	—	14	21		$V_{\text{GE}} = 15\text{V}$
$t_{\text{d}(\text{on})}$	Turn-On Delay Time	—	54	—	ns	$T_J = 25^\circ\text{C}$ $I_C = 9.0\text{A}$, $V_{\text{CC}} = 480\text{V}$ $V_{\text{GE}} = 15\text{V}$, $R_G = 50\Omega$ Energy losses include "tail" and diode reverse recovery
t_r	Rise Time	—	34	—		
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time	—	180	270		
t_f	Fall Time	—	72	110		
E_{on}	Turn-On Switching Loss	—	0.34	—	mJ	See Fig. 9,10,14
E_{off}	Turn-Off Switching Loss	—	0.30	—		
E_{ts}	Total Switching Loss	—	0.64	0.96		
t_{sc}	Short Circuit Withstand Time	10	—	—	μs	$V_{\text{CC}} = 360\text{V}$, $T_J = 125^\circ\text{C}$ $V_{\text{GE}} = 15\text{V}$, $R_G = 50\Omega$, $V_{\text{CPK}} < 500\text{V}$
$t_{\text{d}(\text{on})}$	Turn-On Delay Time	—	51	—	ns	$T_J = 150^\circ\text{C}$, See Fig. 11,14 $I_C = 9.0\text{A}$, $V_{\text{CC}} = 480\text{V}$ $V_{\text{GE}} = 15\text{V}$, $R_G = 50\Omega$ Energy losses include "tail" and diode reverse recovery
t_r	Rise Time	—	37	—		
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time	—	220	—		
t_f	Fall Time	—	160	—		
E_{ts}	Total Switching Loss	—	0.85	—	mJ	
L_E	Internal Emitter Inductance	—	7.5	—	nH	Measured 5mm from package
C_{ies}	Input Capacitance	—	450	—	pF	$V_{\text{GE}} = 0\text{V}$ $V_{\text{CC}} = 30\text{V}$ See Fig. 7 $f = 1.0\text{MHz}$
C_{oes}	Output Capacitance	—	61	—		
C_{res}	Reverse Transfer Capacitance	—	14	—		
t_{rr}	Diode Reverse Recovery Time	—	37	55	ns	$T_J = 25^\circ\text{C}$ See Fig.
		—	55	90		$T_J = 125^\circ\text{C}$ 14
I_{rr}	Diode Peak Reverse Recovery Current	—	3.5	5.0	A	$T_J = 25^\circ\text{C}$ See Fig.
		—	4.5	8.0		$T_J = 125^\circ\text{C}$ 15
Q_{rr}	Diode Reverse Recovery Charge	—	65	138	nC	$T_J = 25^\circ\text{C}$ See Fig.
		—	124	360		$T_J = 125^\circ\text{C}$ 16
$dI_{(\text{rec})\text{M}/dt}$	Diode Peak Rate of Fall of Recovery During t_b	—	240	—	$\text{A}/\mu\text{s}$	$T_J = 25^\circ\text{C}$ See Fig.
		—	210	—		$T_J = 125^\circ\text{C}$ 17

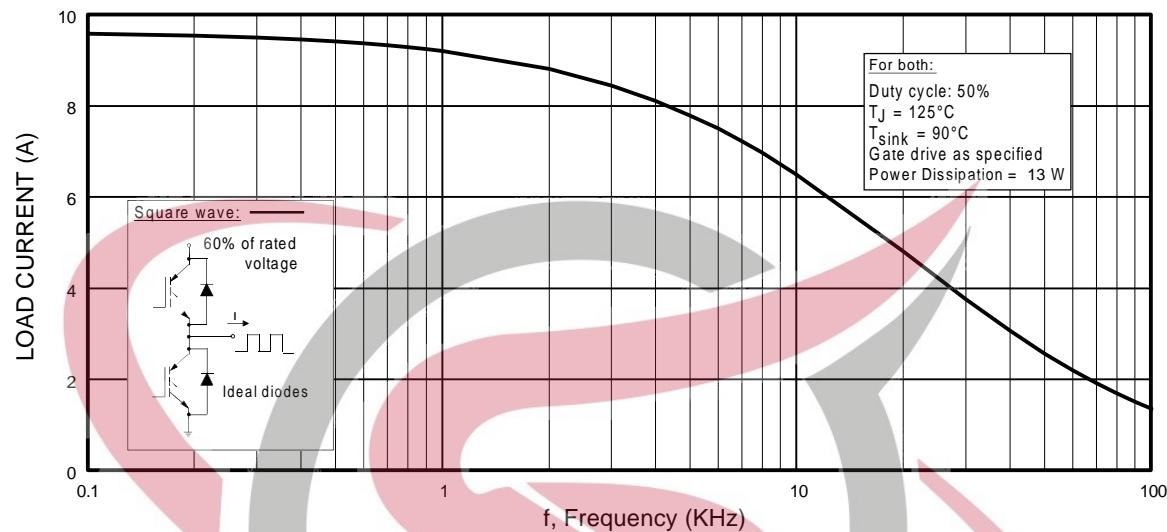


Fig. 1 - Typical Load Current vs. Frequency
 (Load Current = I_{RMS} of fundamental)

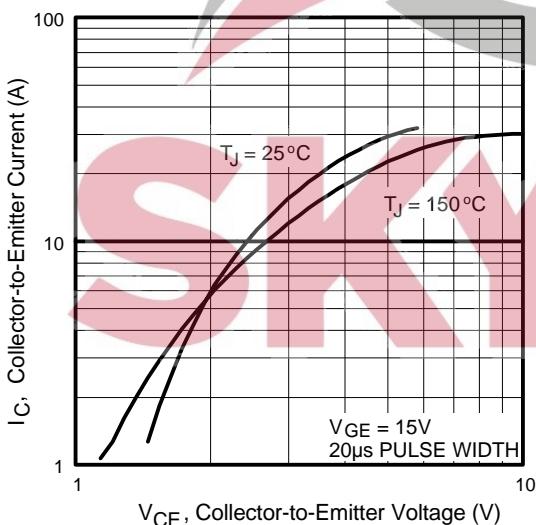


Fig. 2 - Typical Output Characteristics

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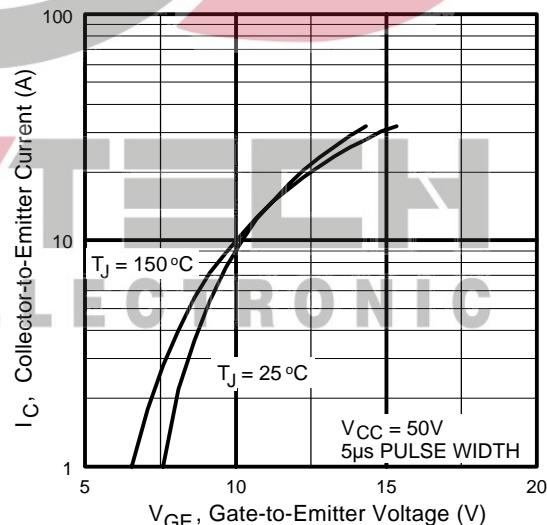


Fig. 3 - Typical Transfer Characteristics

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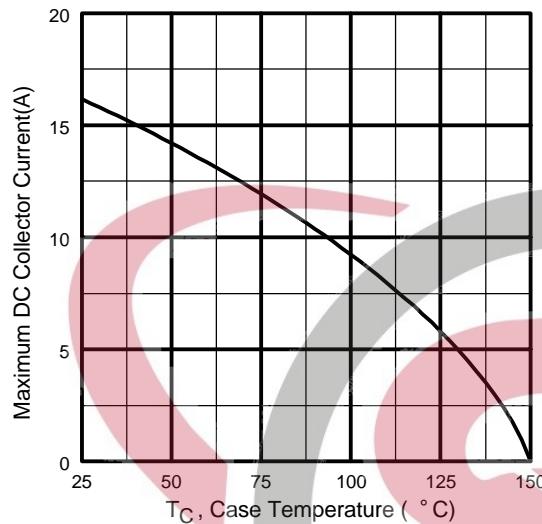


Fig. 4 - Maximum Collector Current vs. Case Temperature

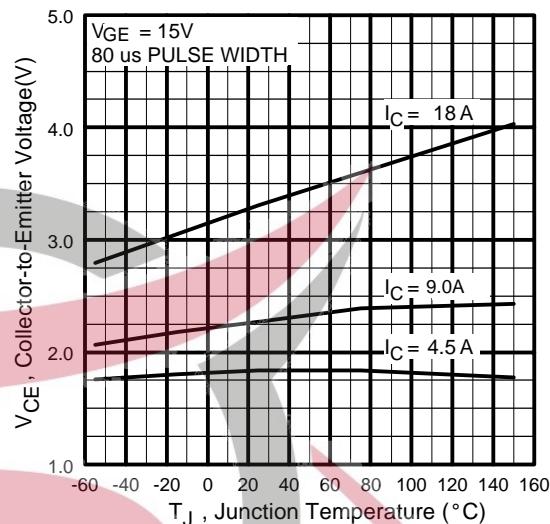


Fig. 5 - Typical Collector-to-Emitter Voltage vs. Junction Temperature

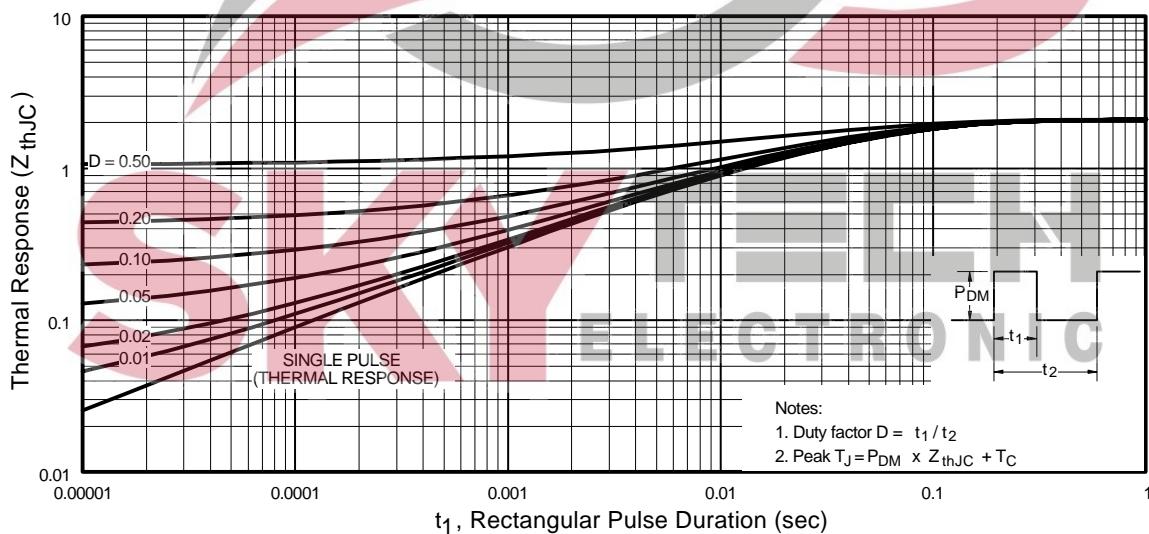
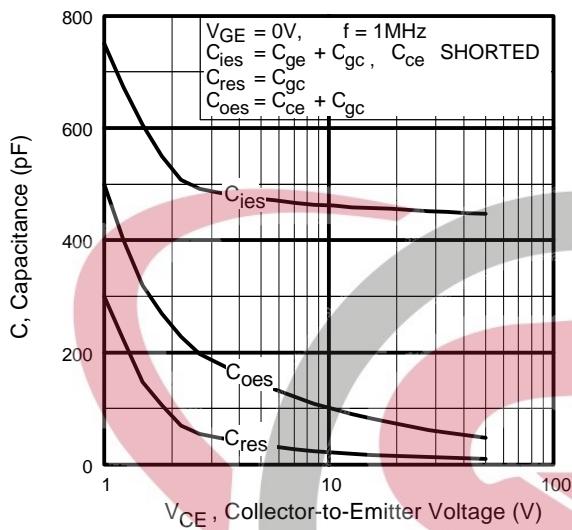
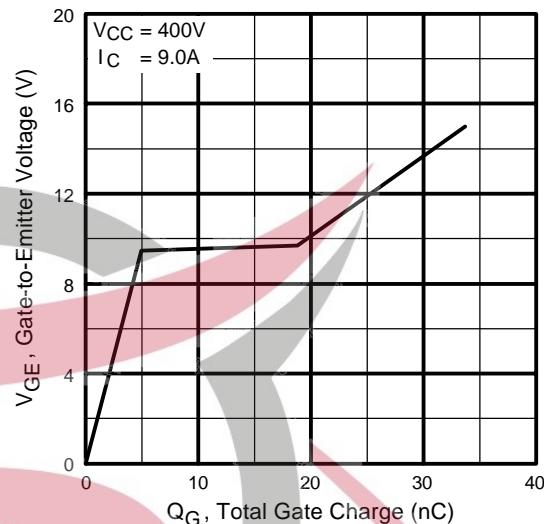


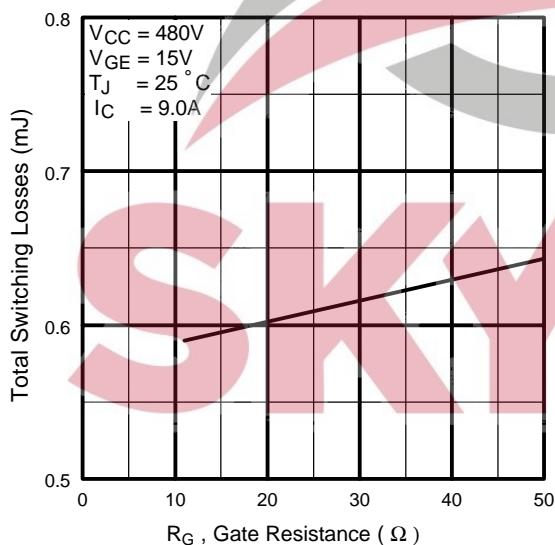
Fig. 6 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



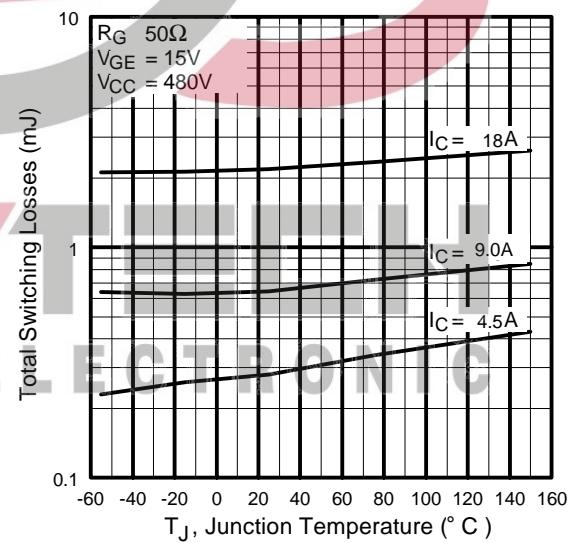
**Fig. 7 - Typical Capacitance vs.
Collector-to-Emitter Voltage**



**Fig. 8 - Typical Gate Charge vs.
Gate-to-Emitter Voltage**



**Fig. 9 - Typical Switching Losses vs. Gate
Resistance**



**Fig. 10 - Typical Switching Losses vs.
Junction Temperature**

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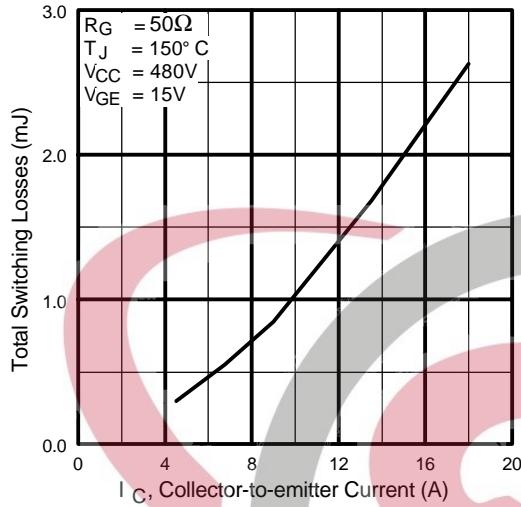


Fig. 11 - Typical Switching Losses vs.
Collector-to-Emitter Current

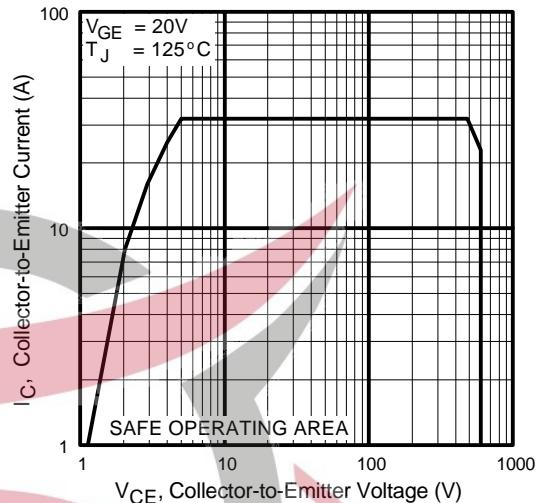


Fig. 12 - Turn-Off SOA

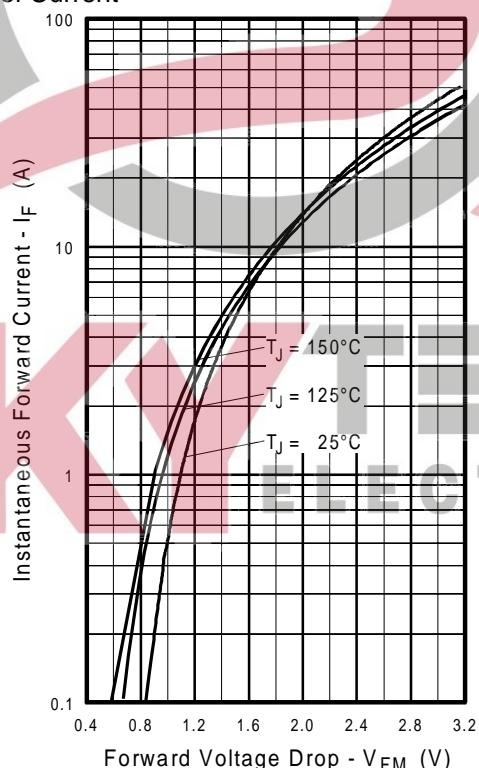


Fig. 13 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

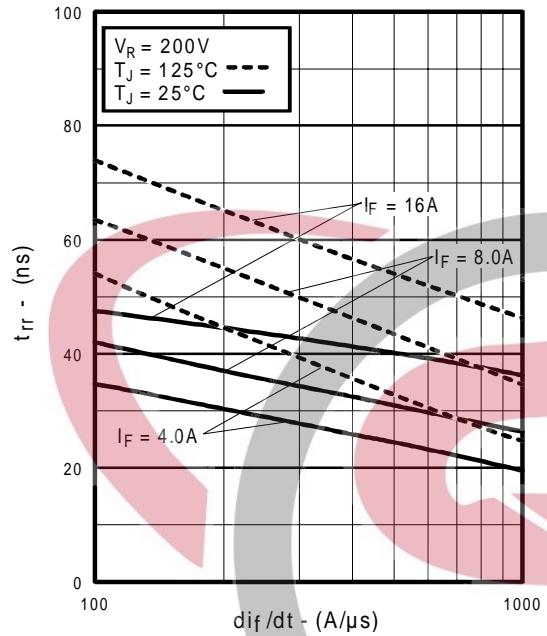


Fig. 14 - Typical Reverse Recovery vs. di_f/dt

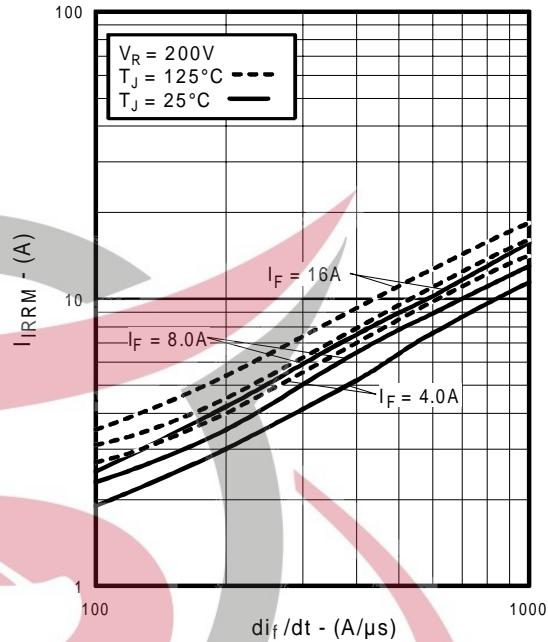


Fig. 15 - Typical Recovery Current vs. di_f/dt

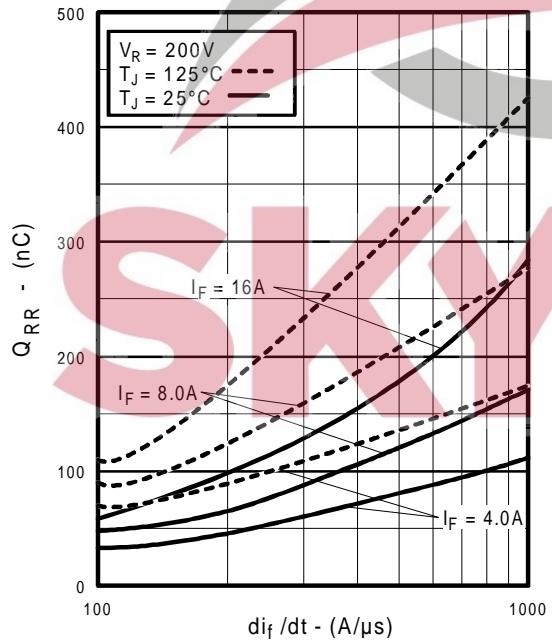


Fig. 16 - Typical Stored Charge vs. di_f/dt

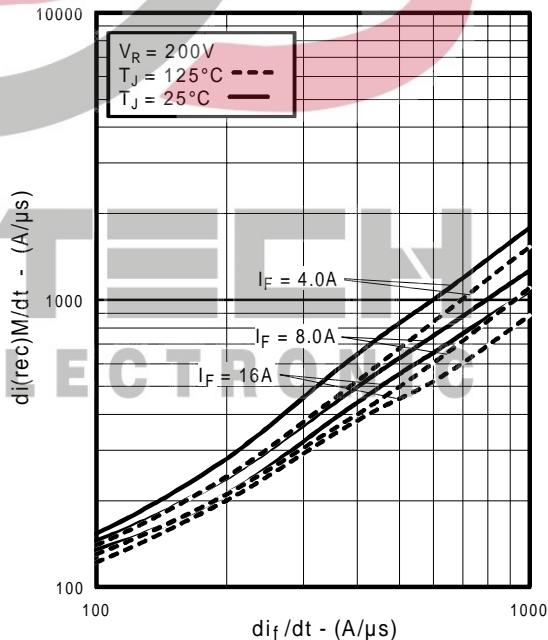


Fig. 17 - Typical dI_{rrM}/dt vs. di_f/dt

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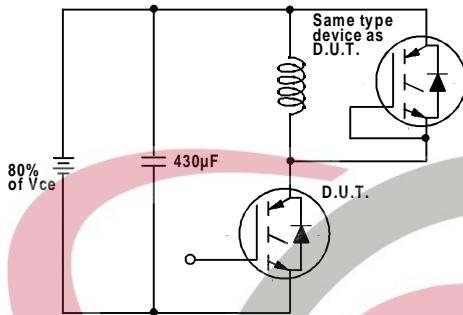


Fig. 18a - Test Circuit for Measurement of
ILM, Eon, Eoff(diode), trr, Qrr, Irr, tdon, tfr, tdooff, tf

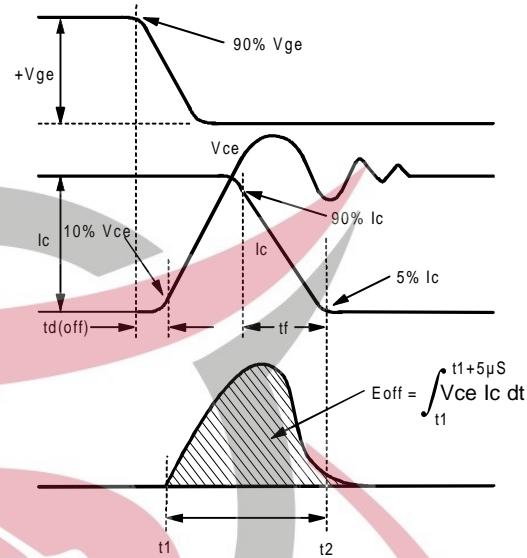


Fig. 18b - Test Waveforms for Circuit of Fig. 18a, Defining
Eoff, tdooff, tf

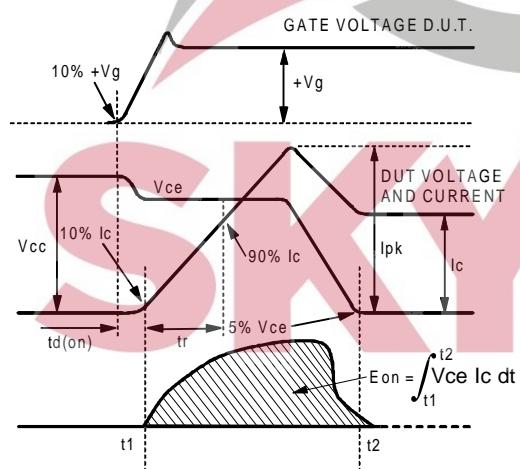


Fig. 18c - Test Waveforms for Circuit of Fig. 18a,
Defining Eon, tdon, tr

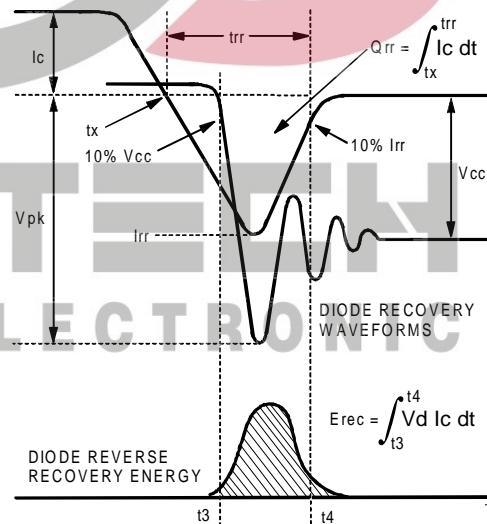


Fig. 18d - Test Waveforms for Circuit of Fig. 18a,
Defining Erec, trr, Qrr, Irr

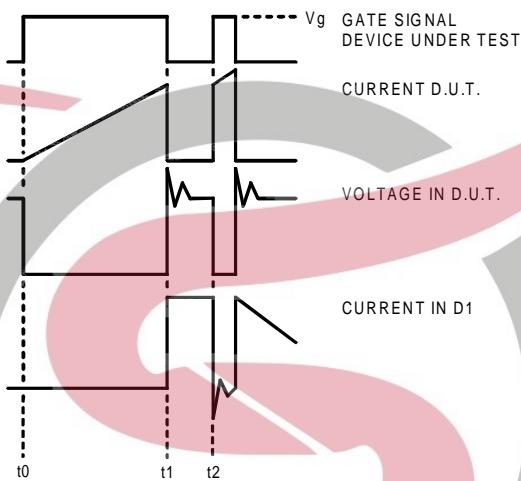


Figure 18e. Macro Waveforms for Figure 18d's Test Circuit

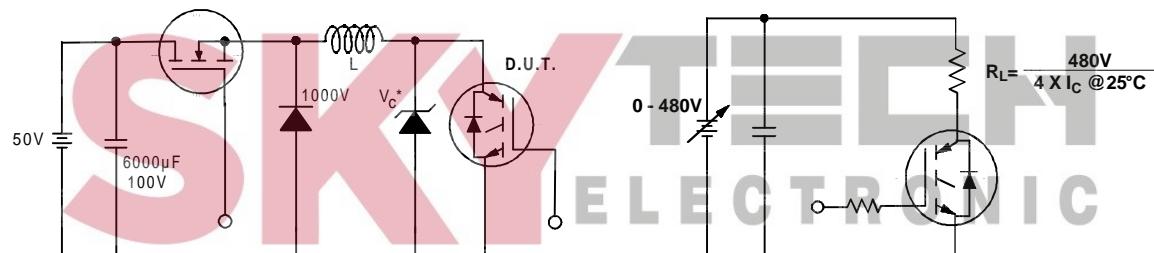


Figure 19. Clamped Inductive Load Test Circuit

Figure 20. Pulsed Collector Current Test Circuit

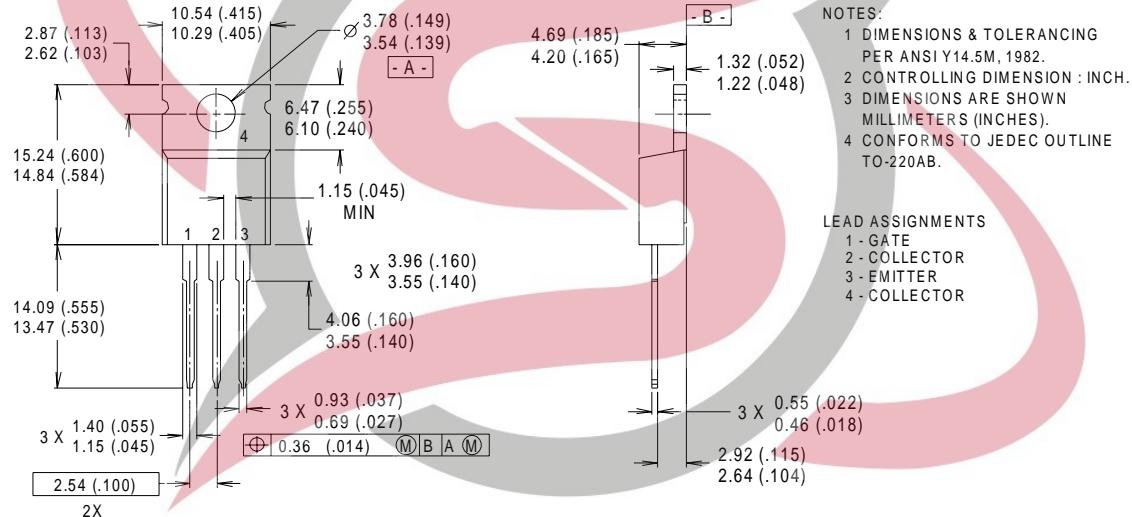
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Notes:

- ① Repetitive rating: $V_{GE}=20V$; pulse width limited by maximum junction temperature (figure 20)
- ② $V_{CC}=80\% (V_{CES})$, $V_{GE}=20V$, $L=10\mu H$, $R_G=50\Omega$ (figure 19)
- ③ Pulse width $\leq 80\mu s$; duty factor $\leq 0.1\%$.
- ④ Pulse width $5.0\mu s$, single shot.

Case Outline — TO-220AB



CONFORMS TO JEDEC OUTLINE TO-220AB

Dimensions in Millimeters and (Inches)

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Data and specifications subject to change without notice. 10/00

Note: For the most current drawings please refer to the IR website at:
<http://www.irf.com/package/>

